



N-Channel Enhancement Mode Power MOSFET **MXD30N100**

DESCRIPTION

The MXD30N100 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

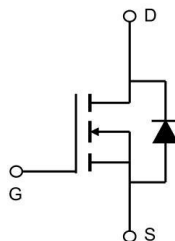
GENERAL FEATURES

- $V_{DS}=30V$, $I_D=100A$
 $R_{DS(ON)}(Typ.)=5.5m\Omega$ @ $V_{GS}=4.5V$
 $R_{DS(ON)}(Typ.)=4.3m\Omega$ @ $V_{GS}=10V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

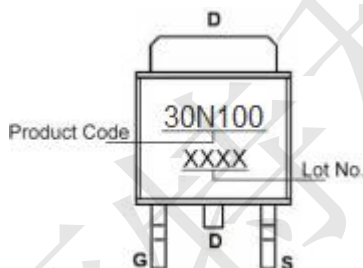
APPLICATION

- Battery management
- Motor controller and driver
- PWM applications
- Load switch

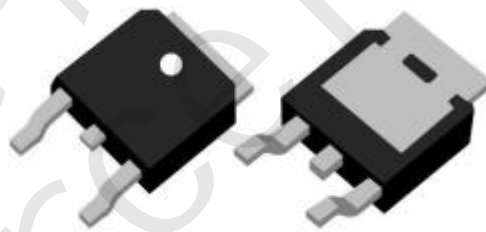
PINOUT



Schematic diagram



Marking and pin Assignment



TO-252-2L top & bottom view

ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MX30N100	-55°C to 175°C	TO-252-2L	-

ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	100	A
Drain Current-Continuous ($T_C=100^\circ C$)	I_D	70	A
Pulsed Drain Current ^(Note1)	I_{DM}	350	A
Maximum Power Dissipation	P_D	110	W
Single Pulse Avalanche Energy ($L=0.5mH$)	E_{AS}	298	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ C$

THERMAL RESISTANCE

Thermal Resistance, Junction-to-Case ^(Note2)	$R_{\theta JC}$	1.36	$^\circ C/W$
---	-----------------	------	--------------

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.



N-Channel Enhancement Mode Power MOSFET **MXD30N100**



ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics (Note2)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.6	2.5	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=30A$	-	5.5	7	m Ω
		$V_{GS}=10V, I_D=30A$	-	4.3	5.5	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=20A$	-	90	-	S
Dynamic Characteristics (Note3)						
Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V, F=1.0MHz$	-	2640	-	pF
Output Capacitance	C_{oss}		-	260	-	pF
Reverse Transfer Capacitance	C_{rss}		-	220	-	pF
Gate Resistance	R_g	$V_{DS}=0V, V_{GS}=0V, F=1.0MHz$	-	7	-	Ω
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=15V, I_D=2A, R_L=1\Omega, V_{GS}=10V, R_G=3\Omega$	-	7.3	-	nS
Turn-on Rise Time	t_r		-	11	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	22	-	nS
Turn-Off Fall Time	t_f		-	5	-	nS
Total Gate Charge	Q_g	$V_{DS}=10V, I_D=20A, V_{GS}=10V$	-	54	-	nC
Gate-Source Charge	Q_{gs}		-	4.5	-	nC
Gate-Drain Charge	Q_{gd}		-	11	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note2)	V_{SD}	$V_{GS}=0V, I_S=1A$	-	-	1.2	V
Diode Forward Current (Note1)	I_S		-	-	45	A

Note 1. Surface Mounted on FR4 Board, $t \leq 10$ sec.
 Note 2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
 Note 3. Guaranteed by design, not subject to product.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Switching Test Circuit

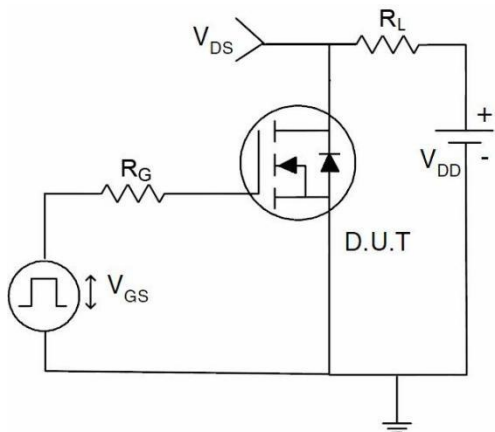


Figure 2. Switching Waveform

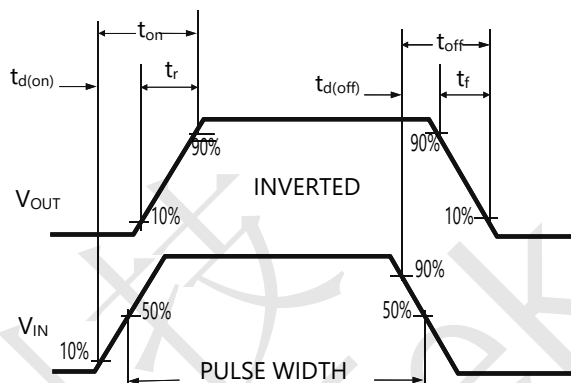


Figure 3. Power Dissipation

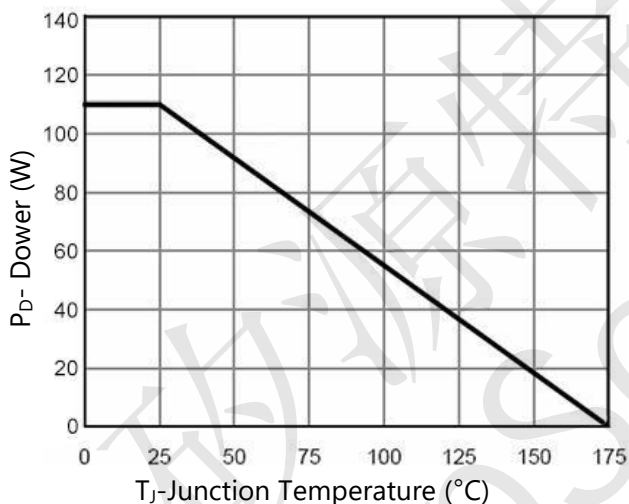


Figure 4. Drain Current

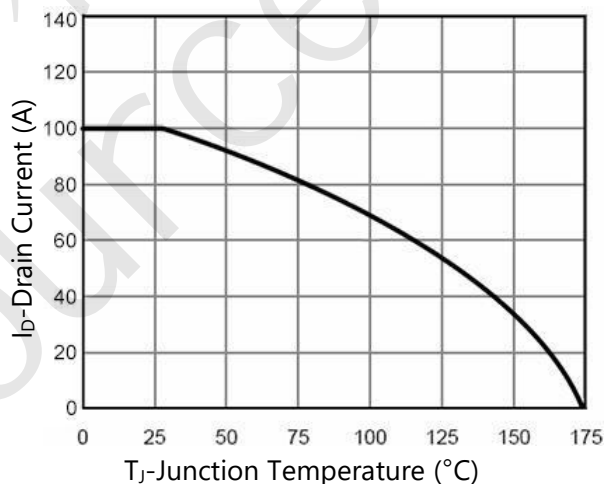


Figure 5. Output Characteristics

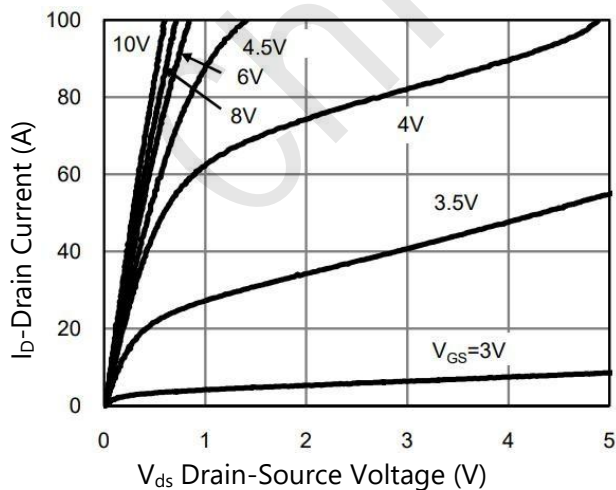
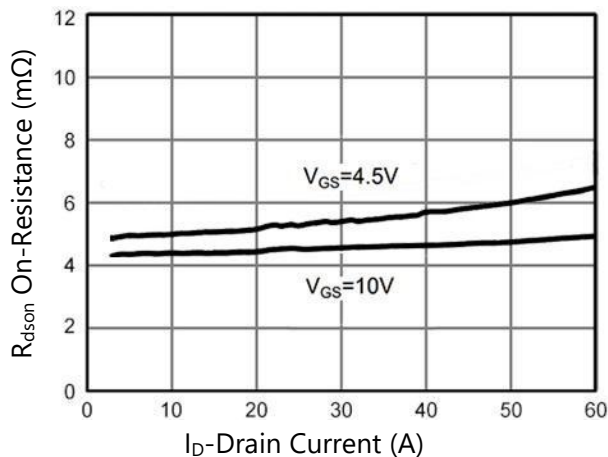


Figure 6. R_{ds(on)} vs Drain Current





TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7. Transfer Characteristics

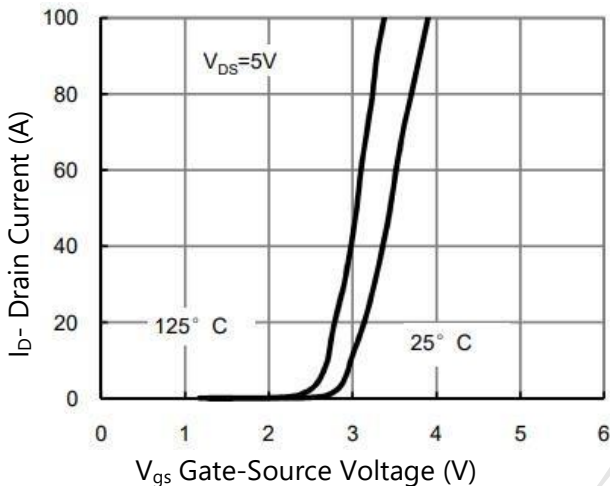


Figure 8. R_{dson} vs Junction Temperature

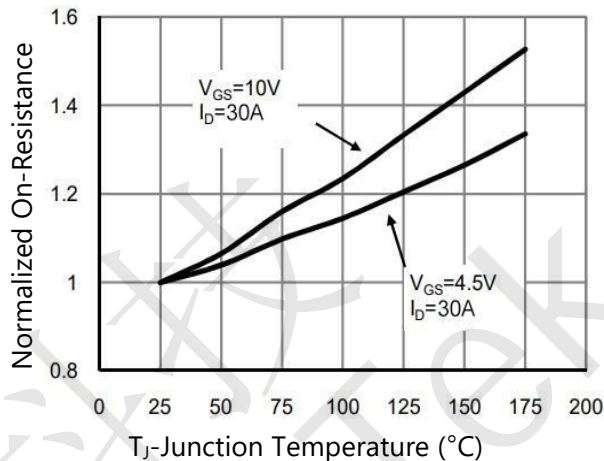


Figure 9. R_{dson} vs V_{gs}

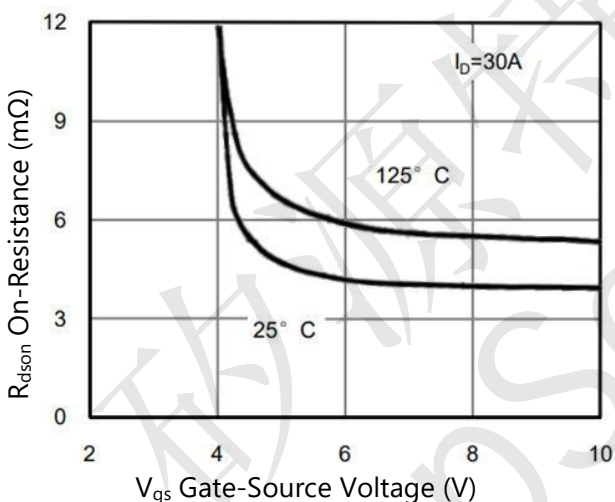


Figure 10. Capacitance vs V_{DS}

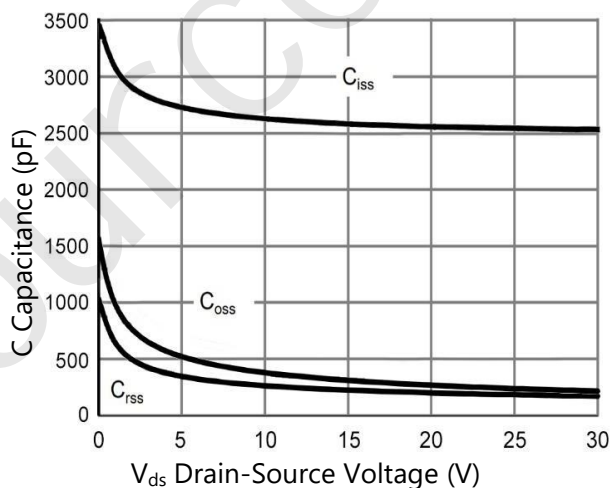


Figure 11. Gate Charge

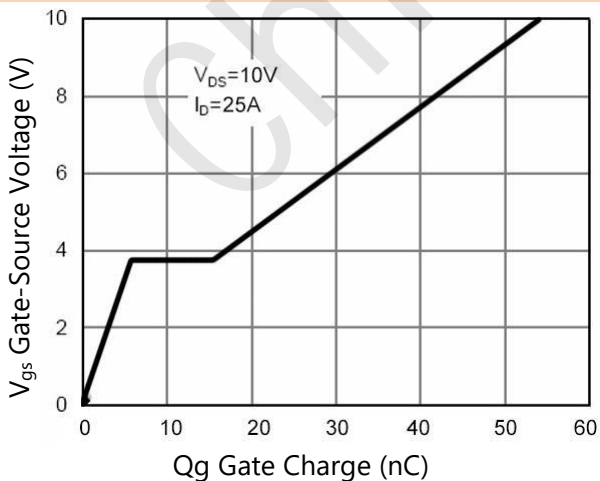
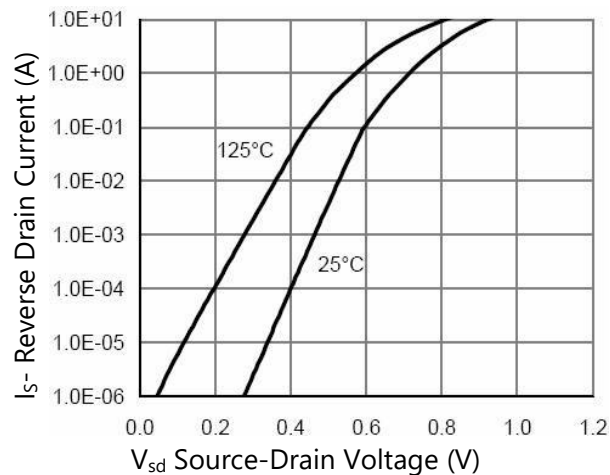


Figure 12. Source- Drain Diode Forward





TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 13. Safe Operation Area

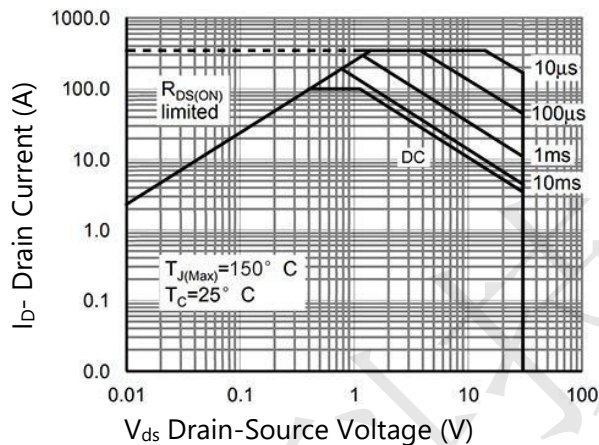
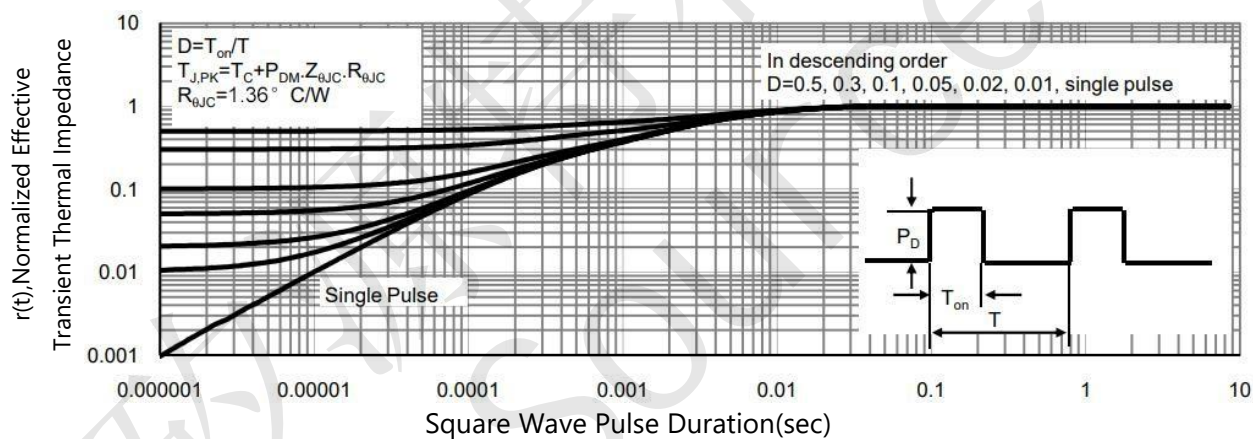


Figure 14. Normalized Maximum Transient Thermal Impedance



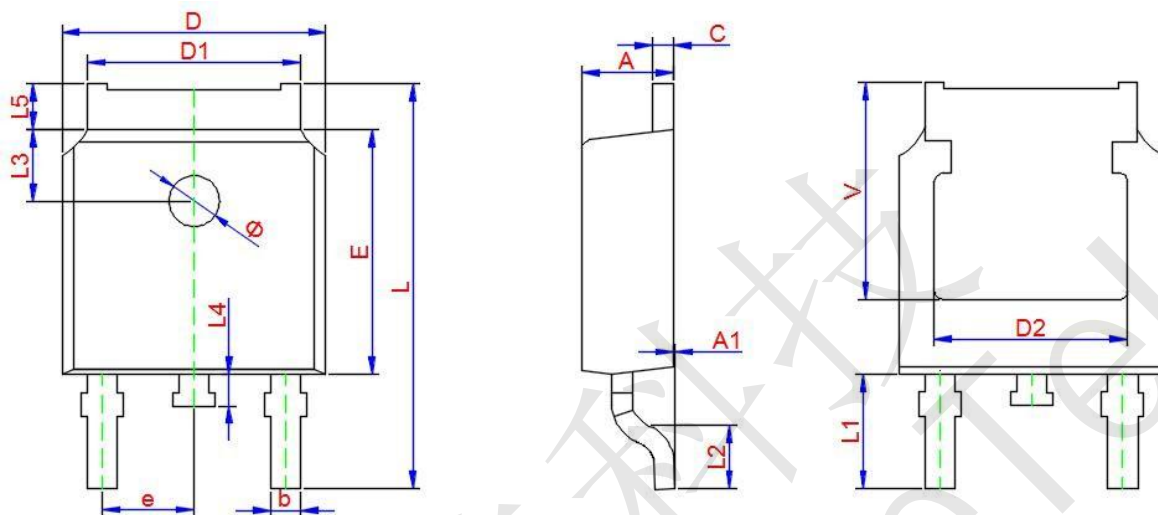


N-Channel Enhancement Mode Power MOSFET **MXD30N100**



PACKAGE INFORMATION

TO-252-2L



Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	2.200	2.300	2.400
A1	0.000	-	0.127
D	6.500	6.600	6.700
D1	5.100	5.330	5.460
C	0.450	0.500	0.600
D2	4.830 TYP.		
E	6.000	6.100	6.200
e	2.186	2.286	2.386
L	9.800	10.100	10.400
L1	2.900 TYP.		
L2	1.400	1.500	1.600
L3	1.800 TYP.		
L4	0.600	0.800	1.000
L5	0.900	-	1.250
Φ	1.100.	-	1.300
θ	0°	-	8°
V	5.350		